



Material Content Data Sheet



Sales Product Name		IFX4949SJ		Issued		17. April 2015		
MA#		MA000998440						
Package		PG-DSO-8-44		Weight*		82.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.577	0.70	0.70	6986	6986
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		434	
	non noble metal	iron	7439-89-6	0.717	0.87		8683	
wire	non noble metal	copper	7440-50-8	29.121	35.26	36.18	352562	361788
	non noble metal	copper	7440-50-8	0.081	0.10	0.10	980	980
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1219
encapsulation	plastics	epoxy resin	-	4.630	5.61		56052	
	inorganic material	silicondioxide	60676-86-0	45.593	55.19	60.92	551986	609257
leadfinish	non noble metal	tin	7440-31-5	0.824	1.00	1.00	9976	9976
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7872	7872
glue	plastics	acrylic resin	-	0.057	0.07		691	
	noble metal	silver	7440-22-4	0.202	0.24	0.31	2450	3141
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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